

Date Created : 2008/10/16
Date Issued On : 2008/10/24
PCN# : Q1080906-B

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:

Name: Constantino, John
E-mail: John.Constantino@fairchildsemi.com
Phone: 408-822-2652

PCN Originator:

Name: Beng Hooi, Swa
E-mail: BH.SWA@fairchildsemi.com
Phone:

Implementation of change:

Expected 1st Device Shipment Date: 2008/11/30

Earliest Year/Work Week of Changed Product: 0849

Change Type Description: Alternate Fab Location, Wafer Diameter

Description of Change (From): Optoelectronics detector devices utilized in the assembly of the attached affected products are currently fabricated at China Resources (CRS) 4 inch fabrication facility located in Hong Kong, China.

Description of Change (To): Optoelectronics detector devices utilized in the assembly of the attached affected products will be fabricated at CRS 6 inch fabrication facility located in Wuxi, China. There will be no detector device, design, die size or die thickness changes for the affected FSID's. Product assembled with detector die manufactured at Wuxi facility will be fully compliant to all publish databook specifications and will be interchangeable with products manufactured at the existing wafer fab location. Quality and reliability will remain at the highest levels already demonstrated with Fairchild existing products.

Reason for Change : Optoelectronic detector devices utilized in the assembly of the attached list of affected products will no longer be fabricated in CRS Hong Kong facility. The planned transfer from CRS Hong Kong facility to their fabrication facility in Wuxi, China may impact the ability to supply existing qualified product during the routine PCN approval cycle for certain affected products. Fairchild will work with customer to manage any identified supply issues that may arise.

Qual/REL Plan Numbers : Q20080059

Qualification :

Passed

Results/Discussion for Qual Plan Number - Q20080059

Test: (High Temperature Op Life) Conditions: 100C Standard:				
Lot	Device	Setpoint	Result	Failure Code
Q20080059AAHTOL	QSC113	168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ABHTOL		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ACHTOL		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ADHTOL		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Test: (High Temperature Reverse Bias) Conditions: 85C, 20V Standard: JESD22-A108				
Lot	Device	Setpoint	Result	Failure Code
Q20080059AAHTRB	QSC113	168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ABHTRB		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ACHTRB		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ADHTRB		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Test: (High Temperature Storage Life) Conditions: 100C Standard: JESD22-A103				
Lot	Device	Setpoint	Result	Failure Code
Q20080059AAHTSL	QSC113	168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ABHTSL		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ACHTSL		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ADHTSL		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Test: (Low Temperature Storage) Conditions: -40C Standard:				
Lot	Device	Setpoint	Result	Failure Code
Q20080059AALTS	QSC113	168-HOURS	0/45	
		500-HOURS	0/45	
		1000	0/45	
Q20080059ABLTS		168-HOURS	0/45	
		500-HOURS	0/45	
		1000	0/45	
Q20080059ACLTS		168-HOURS	0/45	
		500-HOURS	0/45	
		1000	0/45	
Q20080059ADLTS		168-HOURS	0/45	
		500-HOURS	0/45	
		1000	0/45	
Test: (Temperature Cycle) Conditions: -40C, 100C Standard: JESD22-A104				
Lot	Device	Setpoint	Result	Failure Code
Q20080059AATMCL2	QSC113	100-CYCLES	0/45	
		200-CYCLES	0/45	
Q20080059ABTMCL2		100-CYCLES	0/45	
		200-CYCLES	0/45	
Q20080059ACTMCL2		100-CYCLES	0/45	
		200-CYCLES	0/45	

Q20080059ADTMCL2		100-CYCLES	0/45	
		200-CYCLES	0/45	
Test: (Temperature Humidity Biased Test) Conditions: 85%RH, 85C, 5V Standard: JESD22-A101				
Lot	Device	Setpoint	Result	Failure Code
Q20080059AATHBT	QSC113	168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ABTHBT		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ACTHBT		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	
Q20080059ADTHBT		168-HOURS	0/45	
		500-HOURS	0/45	
		1000-HOURS	0/45	

Product Id Description :

Affected FSIDs :

H21A1	H21A2	H21A3
H21A4	H21A5	H21A6
H22A1	H22A2	H22A3
H22A4	H22A5	H22A6
KAR00035	KAR00052	KAR00054
KAR00055A	KAR00055A_NL	KAR00055B
KAR00056	KAR00060A	KAR00061A
KAT00022A	KAT00073B	KAT00073
KAT00122	KAT00124A	KAT00124
KAT00137	KAT00138	KAT00139
KOI00003A	KOI00003	MOC70P1
MOC70P2	MOC70P3	QCK5TR
QCK5	QRB1113	QRB1114
QRB1133	QRB1134	QRD1113
QRD1114	QRD1114_0191K	QRE00034
QSC112CC6R0	QSC112	QSC112_0056K
QSC113C6R0	QSC113	QSC113_0040D
QSC114C	QSC114	QSD122A4R0
QSD122	QSD123A4R0	QSD123
QSD124A4R0	QSD124	QSD722
QSD723	QSD723_0199	QSD724
QSE113E3R0	QSE113	QSE113_0203
QSE114E3R0	QSE114	QSE114_0219
QSE122	QSE214C	QVA11134
QVA11134_0084	QVA21114	QVE00034
QVE00034_0203	QVE00039	QVE00118
QVE00832	QVE11233	